NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE30H10 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

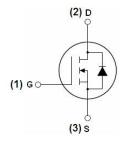
- V_{DS} =30V, I_D =100A $R_{DS(ON)}$ <5.5m Ω @ V_{GS} =10V (Typ:4m Ω)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30H10	NCE30H10	TO-220-3L	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	100	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	70	А
Pulsed Drain Current	I _{DM}	400	Α
Maximum Power Dissipation	P _D	110	W
Single pulse avalanche energy (Note 5)	E _{AS}	350	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$

Thermal Characteristic

I nermal Resistance, Junction-to-Case (Note 2)		Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.36	°C/W	
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Electrical Characteristics (T_A=25°C unless otherwise noted)

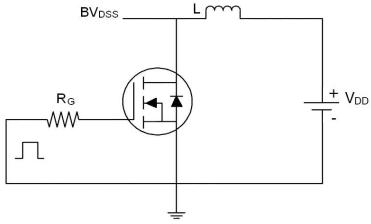
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA 30		-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1	1.6	3	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	4.0	5.5	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =20A	50	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 05\/\/ 0\/		3300		PF
Output Capacitance	Coss	V _{DS} =25V,V _{GS} =0V,		356		PF
Reverse Transfer Capacitance	Crss	F=1.0MHz		308		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	tr	V_{DD} =15 V , I_{D} =30 A	-	160	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =4.5V, R_{GEN} =1.8 Ω	-	25	-	nS
Turn-Off Fall Time	t _f		-	60	-	nS
Total Gate Charge	Qg	\/ 45\/ 00A		70		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =30A,		8.8		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		16.3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =30A	-	-	1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	100	Α
Reverse Recovery Time	Time t_{rr} TJ = 25°C, IF = 30A		-	29	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	32	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LE				

Notes:

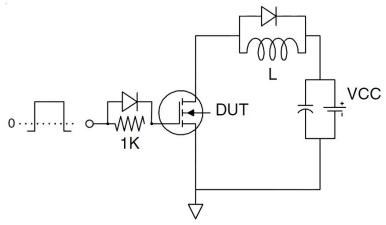
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=15V,VG=10V,L=0.5mH,Rg=25 Ω

Test circuit

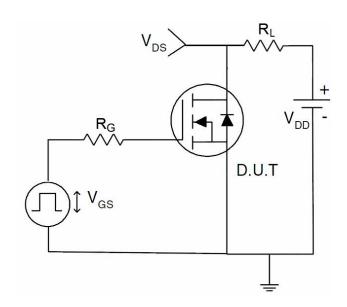
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:





Typical Electrical and Thermal Characteristics (Curves)

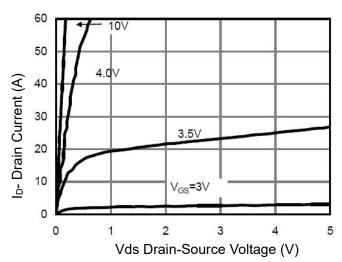


Figure 1 Output Characteristics

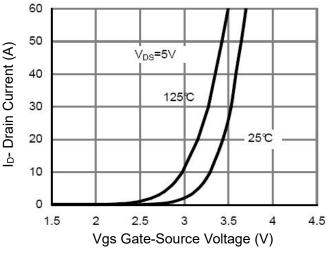


Figure 2 Transfer Characteristics

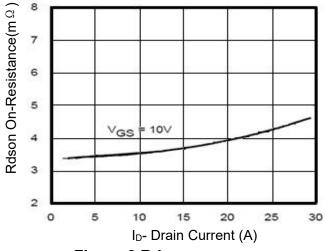


Figure 3 Rdson- Drain Current

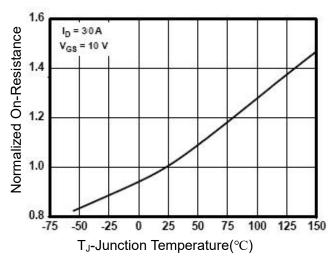


Figure 4 Rdson-JunctionTemperature

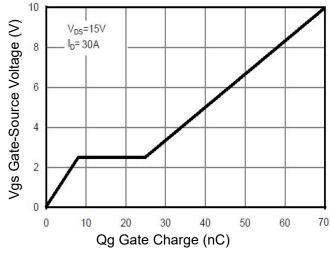


Figure 5 Gate Charge

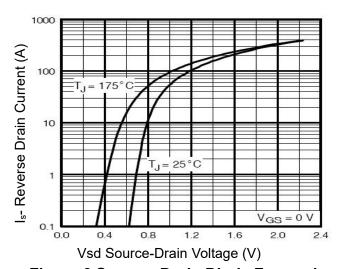


Figure 6 Source- Drain Diode Forward



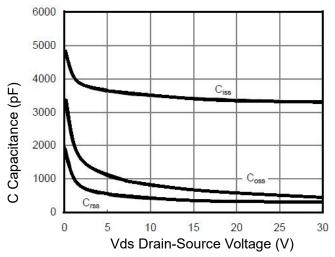


Figure 7 Capacitance vs Vds

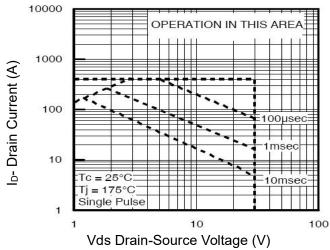


Figure 8 Safe Operation Area

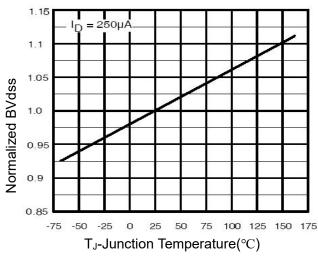


Figure 9 BV_{DSS} vs Junction Temperature

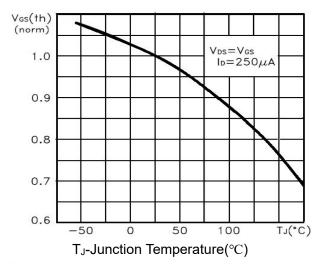


Figure 10 V_{GS(th)} vs Junction Temperature

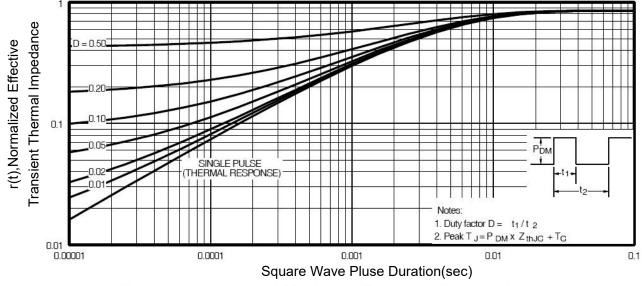
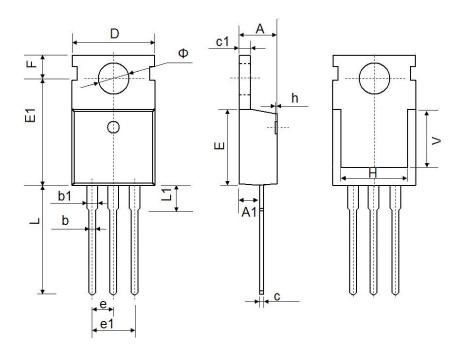


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Comple of	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540	TYP.	0.100	TYP.
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Ф	3.400	3.800	0.134	0.150

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